



4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

IEC 61000-4-2 (ESD): Air - +27/-19kV, Contact - ±16kV

Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)

Product Summary

V _{BR (min)}	I _{PP (max)}	C _{I/O (typ)}
6.2V	6A	0.65pF

Description

This new generation TVS is designed to protect sensitive electronics from the damage due to ESD. The combination of low capacitance and high ESD surge capability makes it ideal for use in high speed ports such as USB 2.0, IEEE1394, HDMI, Laptop and Personal Computers, Flat Panel Displays, Video Graphics Displays, SIM Ports.

Applications

- USB 2.0
- IEEE1394
- SIM Ports
- Portable Electronics
- Computers and Peripheral

Halogen and Antimony Free. "Green" Device (Note 3) Mechanical Data

Case: TSOT26

Features

- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020

Low Clamping Voltage, I/O to V_{SS} Typical 9V at 10A 100ns, TLP Typical 7.7V at 6A 8µs/20µs

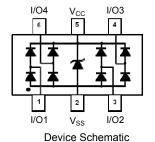
IEC 61000-4-4 (EFT): Level-4 4 Channels of ESD Protection

TLP Dynamic Resistance: 0.25Ω

- Terminals: Matte Tin Finish Annealed over Copper leadframe
- (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.013 grams (approximate)



Top View



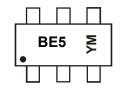
Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT1042-04TS-7	Standard	BE5	7	8	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



BE5= Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	20	13	20	14	20	15	20	16	20	17	20	18
Code	A	4	E	3	())	Е		F	:
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current, per IEC 61000-4-5	I _{PP_I/O}	±6	Α	I/O to V _{SS} , 8/20µs
Peak Pulse Power, per IEC 61000-4-5	P _{PP_I/O}	55	W	I/O to V _{SS} , 8/20µs
Operating Voltage (DC)	V_{DC}	5.5	V	I/O to V _{SS}
ESD Protection – Contact Discharge, per IEC 61000-4-2	V _{ESD_I/O}	±16	kV	I/O to V _{SS}
ESD Protection – Air Discharge, per IEC 61000-4-2	V _{ESD_I/O}	+27/-19	kV	I/O to V _{SS}
Operating Temperature	T _{OP}	-55 to +85	°C	_
Storage Temperature	T _{STG}	-55 to +150	°C	_

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P_{D}	300	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R_{ hetaJA}$	417	°C/W

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

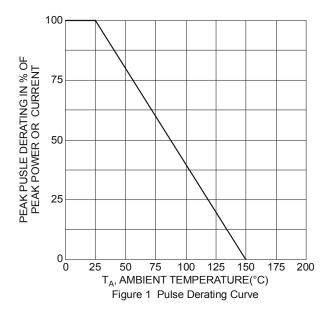
Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	VRWM	_	_	5.0	V	V _{CC} to V _{SS}
Reverse Current (Note 6)	I _{R(} V _{cc to} V _{ss)}	_	-	1.0	μA	$V_R = V_{RWM} = 5V$, V_{CC} to V_{SS}
Reverse Current (Note 6)	I _{R(IO to} V _{ss)}	-	ı	0.5	μA	$V_R = V_{RWM} = 5V$, any I/O to V_{SS}
Reverse Breakdown Voltage	V _{BR}	6.2	1	-	V	I _R = 1mA, V _{CC} to V _{SS}
Forward Clamping Voltage	V_{F}	-1.0	-0.8	-	V	I _F = -15mA, V _{CC} to V _{SS}
Reverse Clamping Voltage(Note 7)	$V_{C}V_{cc}$	_	6.3	-	V	I _{PP} = 9A, V _{CC} to V _{SS} , 8/20 μs
	V _{C_I/O}	_	7.7	9	V	I _{PP} = 6A, I/O to V _{SS} , 8/20 μs
ESD Clamping Valtage	$V_{ESD}V_{cc}$	_	6.8	-	V	TLP, 10A, tp = 100 ns, V_{CC} to V_{SS} , per Fig. 8
ESD Clamping Voltage	V _{ESD_I/O}	_	9	-	V	TLP, 10A, tp = 100 ns, I/O to V _{SS} , per Fig. 8
Dynamia Basistanas	R _{DIF} _V _{cc}	_	0.1	-	Ω	TLP, 10A, tp = 100 ns, V_{CC} to V_{SS}
Dynamic Resistance	R _{DIF_I/O}	_	0.25	-	Ω	TLP, 10A, tp = 100 ns, I/O to V _{SS}
Channel Input Capacitance	C _{I/O to} V _{SS}	_	0.65	0.8	pF	V _R = 2.5V, V _{CC} = 5V, f = 1MHz
Variation of Channel Input Capacitance	$\Delta C_{I/O}$	-	0.02	_	pF	V _{CC} = 5V, V _{SS} = 0V, I/O = 2.5V, f = 1MHz, T = +25°C , I/O_x to V _{SS} – I/O_y to V _{SS}

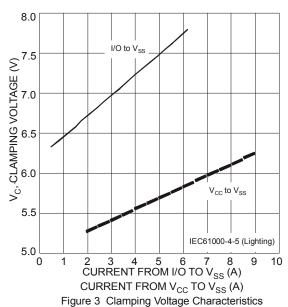
Notes:

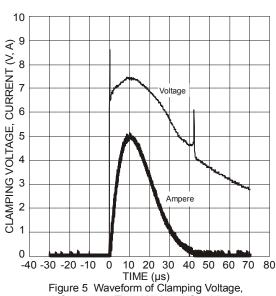
- 5. Device mounted on Polymide PCB pad layout (2oz copper) as shown on Diodes Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

 6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an $8x20\mu s$ peak pulse current (I_{pp}) waveform.









Current vs. Time (8/20µs, I/O to V_{SS})

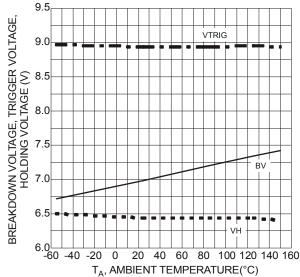


Figure 2 Breakdown Voltage, Trigger Voltage, Holding Voltage vs. Ambient Temperature

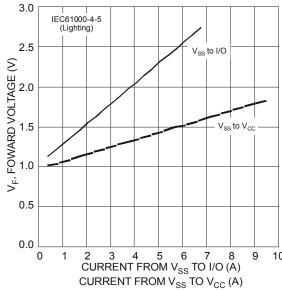
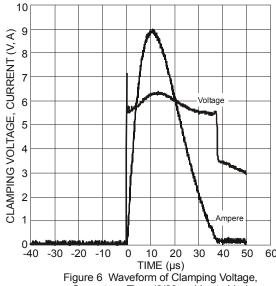
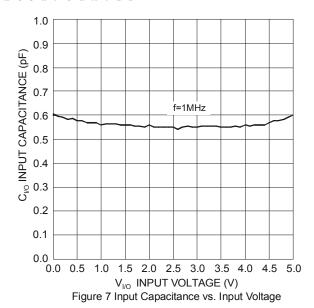


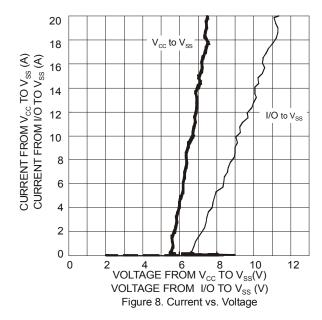
Figure 4 Forward Voltage Characteristics



Current vs. Time (8/20µs, V_{CC} to V_{SS})

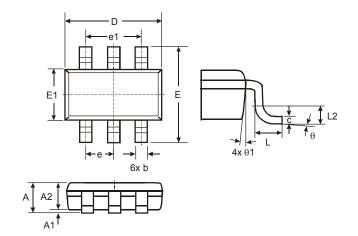






Package Outline Dimensions

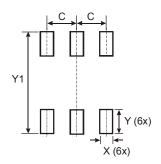
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



TSOT26								
Dim	Min	Max	Тур					
A	-	1.00	-					
A1	0.01	0.10	-					
A2	0.84	0.90	_					
D	_	_	2.90					
Е	_	_	2.80					
E1	_	-	1.60					
b	0.30	0.45	_					
С	0.12	0.20	_					
е	_	_	0.95					
e1	_	-	1.90					
L	0.30	0.50						
L2	_	-	0.25					
θ	0°	8°	4°					
θ1	4°	12°	_					
All D	All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.950
X	0.700
Y	1.000
Y1	3.199



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